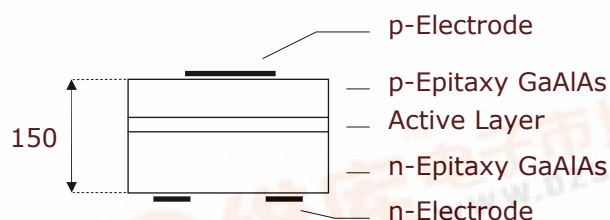
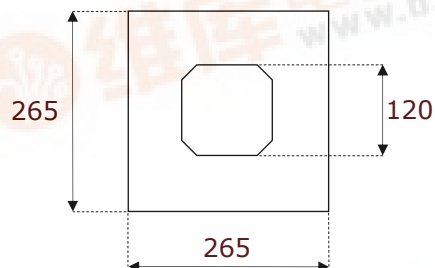


**RED**

**Item No.: 115260**

1. This specification applies to GaAlAs / GaAlAs LED Chips (substrate removed)
2. Structure
  - 2.1 Mesa structure
  - 2.2 Electrodes
 

|                  |          |
|------------------|----------|
| p-side (anode)   | Au alloy |
| n-side (cathode) | Au alloy |
3. Outlines (dimensions in microns)



Wire bond contacts can also be circular or square

4. Electrical and optical characteristics (T=25°C)

| Parameter            | Symbol      | Conditions            | min | typ  | max  | Unit          |
|----------------------|-------------|-----------------------|-----|------|------|---------------|
| Forward voltage      | $V_F$       | $I_F = 20 \text{ mA}$ |     | 1,90 | 2,30 | V             |
| Reverse current      | $I_R$       | $V_R = 5 \text{ V}$   |     |      | 10   | $\mu\text{A}$ |
| Luminous intensity * | $I_V$       | $I_F = 20 \text{ mA}$ | 12  | 16   |      | mcd           |
|                      |             | $I_F = 10 \text{ mA}$ | 6   | 8    |      |               |
| Peak wavelength      | $\lambda_P$ | $I_F = 20 \text{ mA}$ |     | 660  |      | nm            |

Brightness measurement at OSA on gold plate

5. Packing

Dice on adhesive film with 1) wire bond side on top  
2) back contact on top

6. Labeling

| Type | Lot No. | $I_V$ typ<br>min<br>max | Quantity |
|------|---------|-------------------------|----------|
|------|---------|-------------------------|----------|